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For Immediate Release

## **Banpil Optical Interconnects Patent Awarded by USPTO**

**SANTA CLARA, California, March 15, 2015** -- Banpil Photonics, Inc., a leading company expanding the boundaries of optics and electronics through innovations, today announced that the United States Patent and Trademark Office (USPTO) has awarded it an important seminal optical interconnect patent covering stackable optoelectronics chip-to-chip interconnects technology.

The Banpil Interconnect IP portfolio, which encapsulates its high-speed interconnects platform technology, is by far the most advanced available today. It now totals over 25 patents in the company's overall interconnects patent portfolio, which addresses the bottleneck between signal conversion between optics and electrical components to accommodate both in current and future high-speed systems requirements.

In current and future IT environments, the demand for higher speeds (also referred to as high-bandwidth) from the smallest devices to computing systems up to global networks, are driven by the increasing higher level of integration within electrical integrated circuits (ICs), with corresponding increases in pin connections per IC, soon to exceed 10,000 interconnections, and higher densities for off-chip interconnections, all demanding novel approaches to be sustainable. More frequently, optical input/output (I/O) is being used in IT systems to transmit data between system components as it is able to attain higher system bandwidth with lower data losses than conventional I/O methods.

Banpil's innovation enables super high-speed electrical and optical interconnects or terabit interconnects for chip-to-chip interconnection necessary for both on-chip and off-chip interconnects to support and sustain current and next-generation IT systems. It has a broad range of applications in computing and communications from broadband portable devices (PC, tablets, and smart phones) to supercomputers, high-speed servers, routers, high-capacity storage systems, data centers, on-demand gaming systems, imaging and networking systems capable of telepresence anywhere on the globe.

Banpil has already demonstrated its high-speed low-power interconnect platform technology. The company welcomes opportunities to work with system vendors and PCB makers to explore new or enhanced applications including joint product development, technology licensing, strategic manufacturing partnerships as well as investors.

### **About Banpil Photonics, Inc.**

Banpil Photonics is expanding the boundaries of optics and electronics through innovations. Banpil develops and manufactures next generation multispectral image sensors for automotive & medical imaging systems, security & surveillance, and machine vision applications; high-efficiency energy harvesting devices for energy applications; and low-power, high-speed electrical interconnects for chip-to-chip, chip-to-board, board-to-board, and rack-to-rack applications in high-performance computing and networking. The company has an extensive IP portfolio available for licensing. For more information, visit [www.banpil.com](http://www.banpil.com).

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